SP8715

1100MHz Very Low Current Multi-Modulus Divider

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Features

- Operation to 1100MHz
- Very Low Power
- Single Supply Operation 2.7V to 5.25V
- Power Down Facility for Battery Economy
- Latched Modulus Control Input
- Push Pull Output Drive
- ESD Protection on All Pins†

Applications

- Cellular Telephones
- Cordless Telephones
- Mobile Radio

† ESD precautions must be observed

Ordering Information

SP8715/IG/MPAS	Industrial Temperature Range Miniature Plastic SOIC Package
SP8715/IG/MPAC	As Above supplied on Tape and Reel

Description

The SP8715 is a switchable divide by 64/65, 128/129 programmable divider which is guaranteed to operate up to 1100MHz. It will operate from a supply of 2.7V to 5.25V and requires typically 3.6mA (including the output current). It also features a power down facility for battery economy.

The RF inputs are internally biased and should be capacitively coupled to the signal source. The output is designed to interface with CMOS synthesisers.

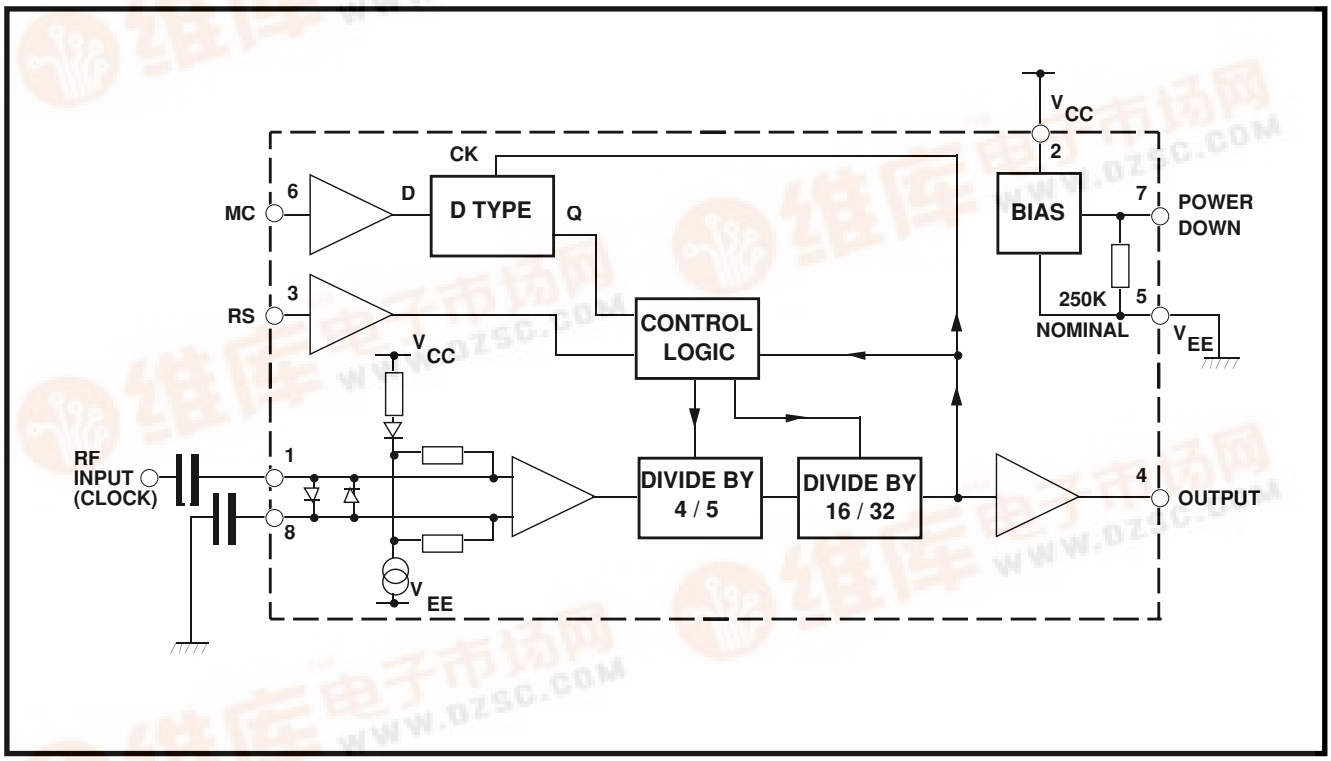
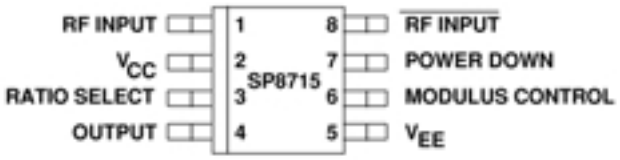


Figure 1 Block Diagram



MP8

Figure 2 Pin Connections

Absolute Maximum Ratings

Supply voltage (V_{EE}=0V)	(note 1)	-0.5V to 7V
Control and RF inputs, RF output (V_{EE} =0V)	(note 1)	-0.5V to V_{CC}+0.5V
RF input current	(note 1)	10mA
Operating temperature		-40°C to +85°C
Storage temperature range		-55°C to +150°C
Maximum junction temperature		+150°C

NOTE 1. Duration <2 minutes.

Electrical Characteristics

Guaranteed over the following conditions (unless otherwise stated):

V_{CC}=+2.7V to +5.25V (with respect to V_{EE}), Output load (pin 4) = 10pF, T_{amb} = -40°C to +85°C (note 2)

Characteristic		Value			Units	Conditions
		Min.	Typ.	Max.		
Supply current	(note 3)		3.6	4.2	mA	Power down input low
Supply current	(note 3)		8	50	µA	Power down input high
Power down high		V_{CC}-0.5		V_{CC}	V	
Power down low		0		V_{CC}-2.0	V	
Modulus control high	(note 4)	0.6V_{CC}		V_{CC}	V	Divide by 64 or 128
Modulus control low	(note 4)	0		0.4V_{CC}	V	Divide by 65 or 129
Ratio select high	(note 4, 9)	0.6V_{CC}		V_{CC}	V	Divide by 64 or 65
Ratio select low	(note 4, 9)	0		0.4V_{CC}	V	Divide by 128 or 129
Max. sinewave input frequency		1100			MHz	See Figure 5
Min. sinewave input frequency				200	MHz	See Figure 5
Min. RF input voltage				50	mV RMS	RF input 200MHz to 1100MHz. See Figure 5
Max. RF input voltage		200			mV RMS	RF input 200MHz to 1100MHz. See Figure 5

Electrical Characteristics (Continued)

Guaranteed over the following conditions (unless otherwise stated):
V_{CC}=+2.7V to +5.25V (with respect to V_{EE}), Output load (pin 4) = 10pF, T_{amb} = -40°C to +85°C (note 2)

Characteristic	Value			Units	Conditions
	Min.	Typ.	Max.		
Output level (pin 4)	500	600			mV p-p
Modulus set-up time, t_s (notes 5,6,8)	20			ns	RF input = 1GHz
Modulus hold time, t_h (notes 6,8)			1	ns	RF input = 1GHz
Power down time, t_{pd} (notes 7,8)			10	µs	See Figure 9
Power down recovery time, t_{pu} (notes 7,8)			6	µs	See Figure 9

NOTES
2. All electrical testing is performed at +85°C.
3. Typical values are measured at +25°C and V_{CC} = +5V.
4. Modulus Control and Ratio Select are high impedance inputs which can be driven directly by standard CMOS outputs.
5. Modulus control is latched at the end of the previous cycle.
6. See Figure 4.
7. See Figure 8.
8. These parameters are not tested but are guaranteee by design.
9. The ratio select pin is not intended to be switched dynamically.

OPERATING NOTES

The RF inputs are biased internally and are normally coupled to the signal source with suitable capaitors.

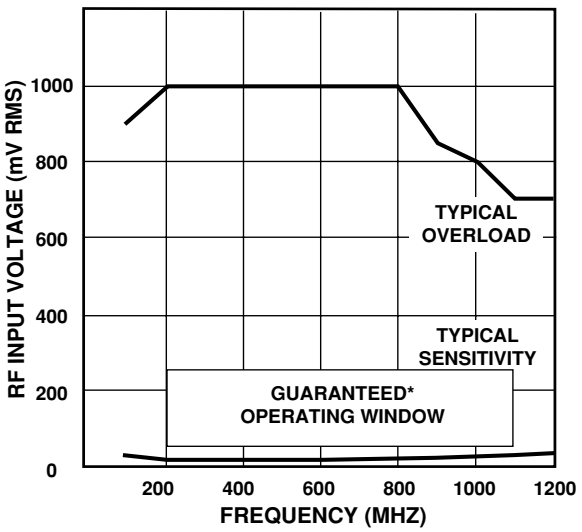
The output stage has a novel design and is intended to drive a CMOS synthesiser input. External pull-down resistors or circuits are not required. The SP8715 is not suitable for driving TTL or similar devices.

The device will operate down to DC frequencies for non-sinusoidal signals provided that the input slew rate is better than 100V/µs.

POWER DOWN (pin 7) is connected internally to a pull-down resistor. If the battery economy facility is not used, pin 7 should be either left unconnected or connected to V_{EE}.

Ratio Select (Pin 3)	Modulus Control (Pin 6)	Division Ratio
L	L	129
L	H	128
H	L	65
H	H	64

Table 1 Truth Table



* Tested as specified in table of Electrical Characteristics

Figure 3 Typical Input Characteristics

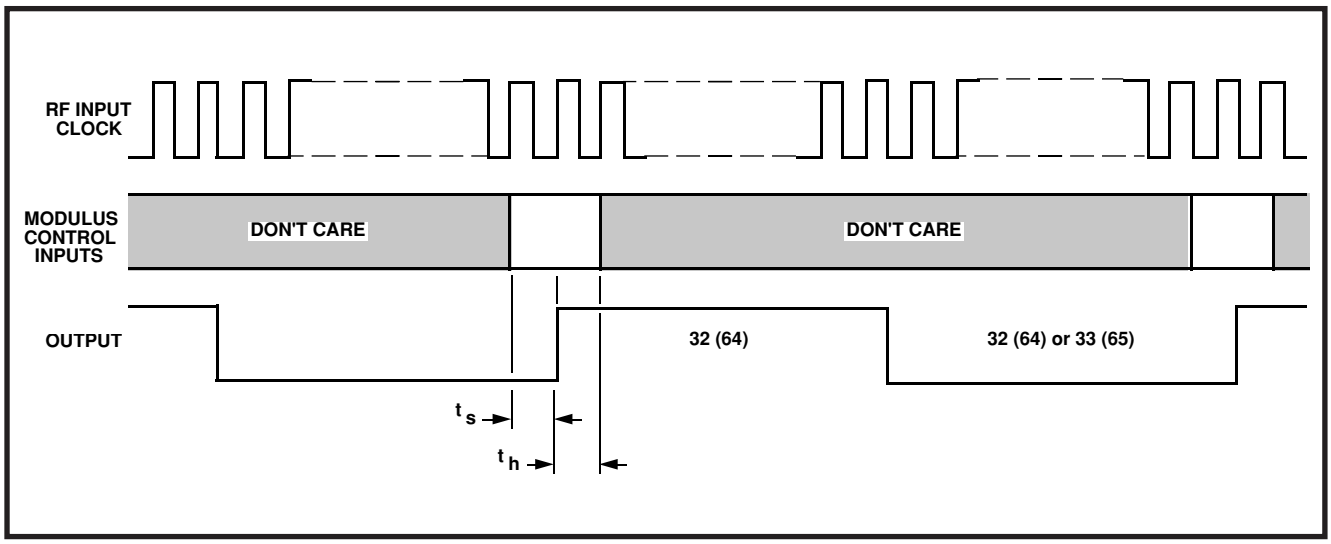


Figure 4 Modulus Control Timing Diagram

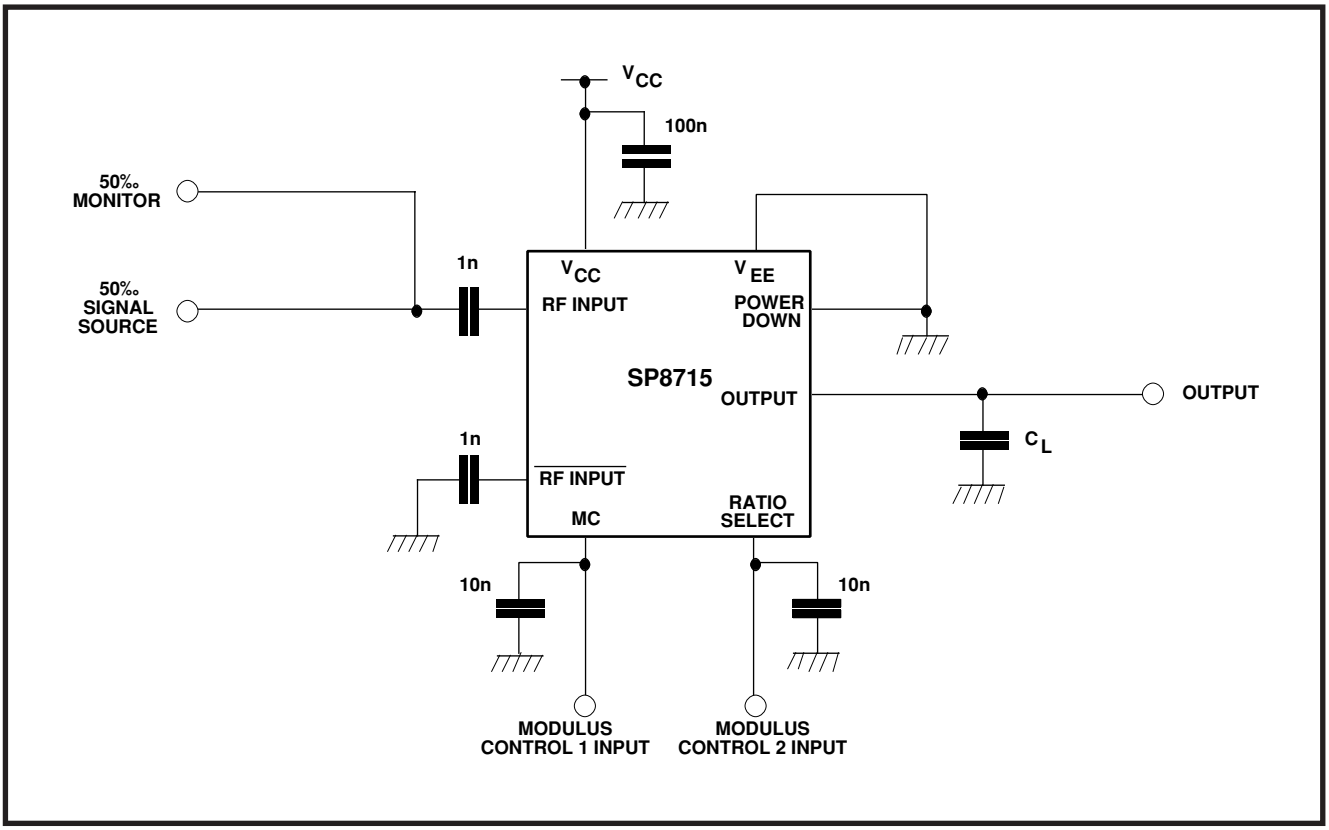


Figure 5 Toggle Frequency Test Circuit

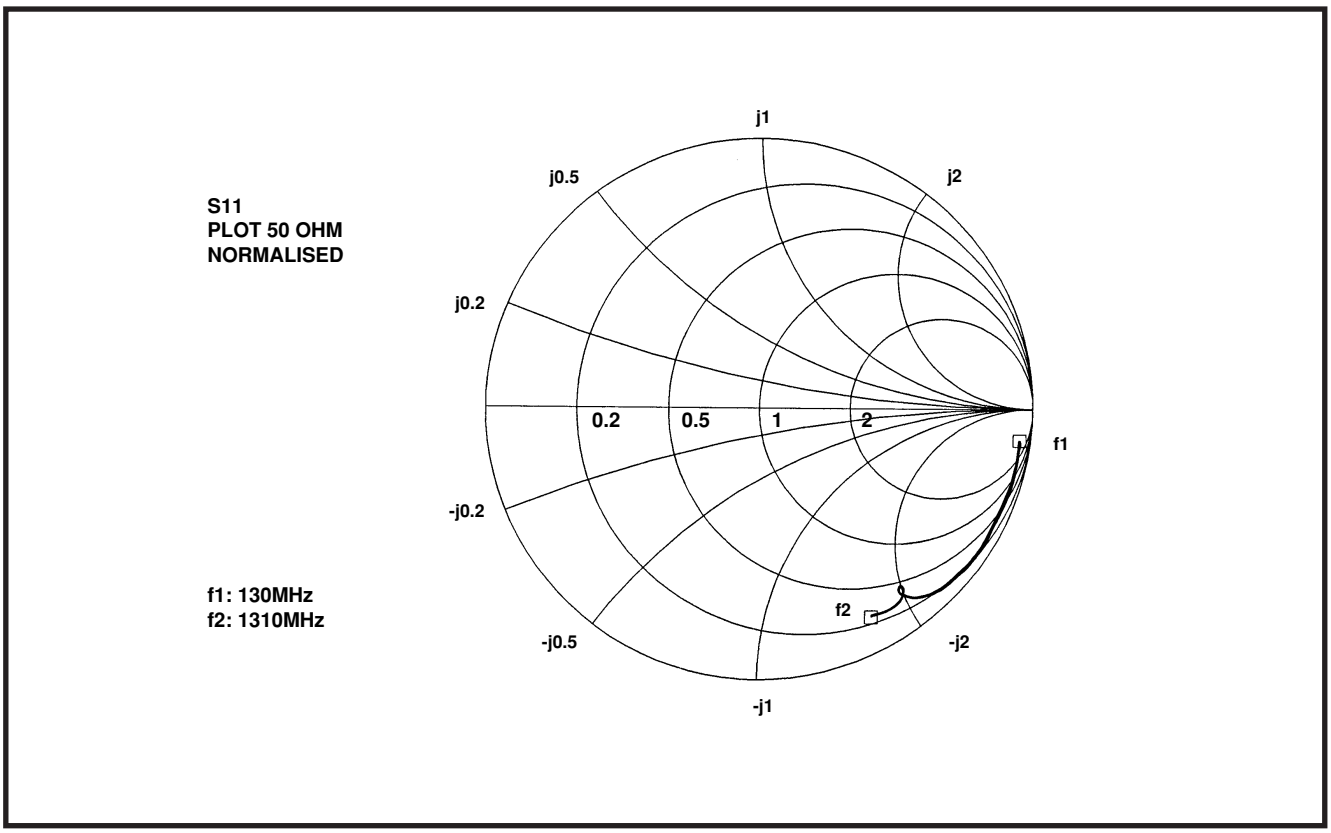


Figure 6 Typical S11 parameter for pin 1. V_{CC} = +5.0V

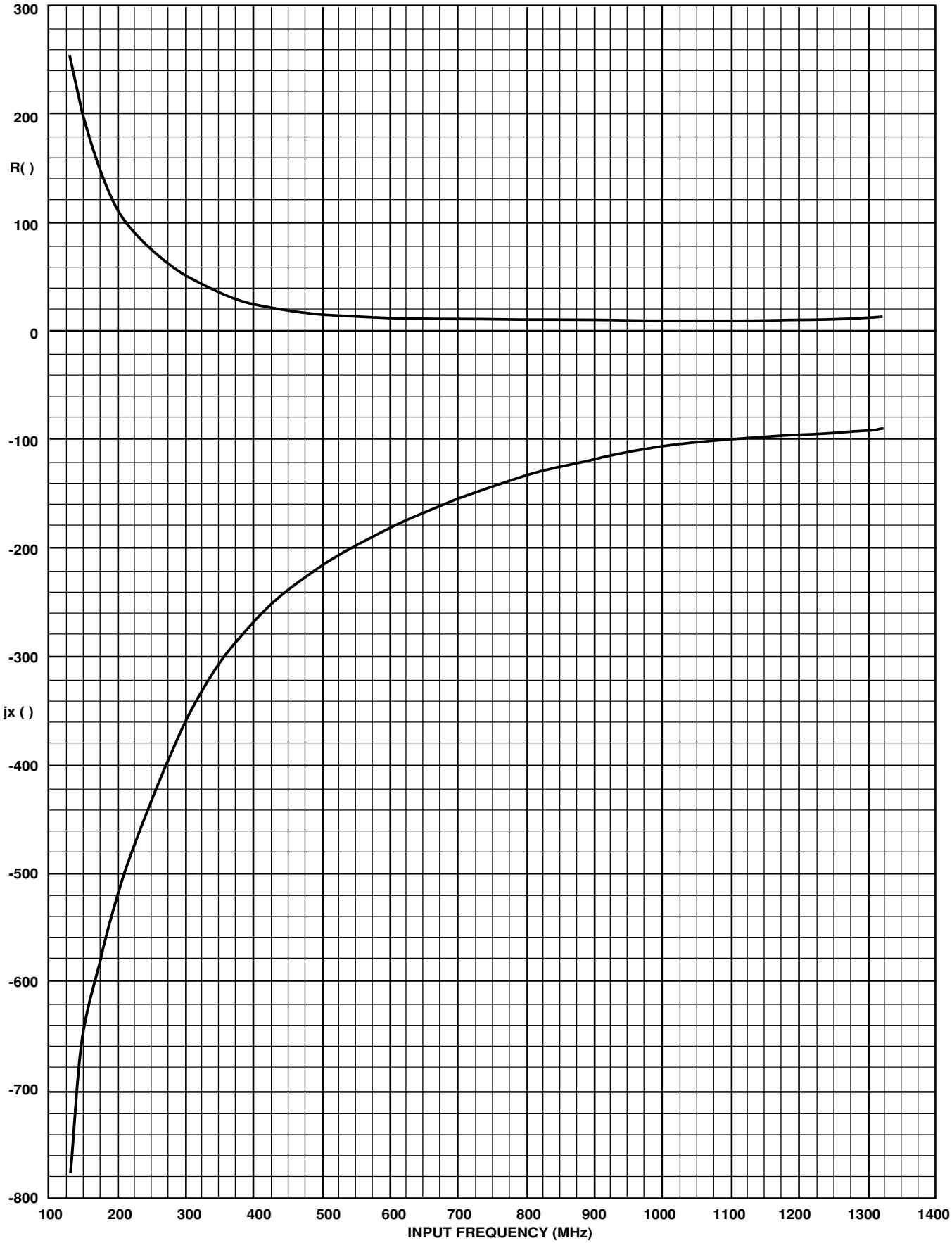


Figure 7 Typical Input Impedance v. Frequency

FREQ-MHZ	R (Ω)	jx (Ω)
130.000	255.068	-733.538
153.600	153.362	-688.623
177.200	153.330	-583.339
200.800	115.187	-545.839
224.400	88.649	-482.377
248.000	80.815	-441.798
271.600	71.050	-411.502
295.200	56.207	-369.645
318.800	39.526	-346.620
342.400	41.338	-323.129
366.000	38.779	-304.804
389.600	39.210	-280.556
413.200	23.809	-269.674
436.800	21.221	-255.279
460.400	27.545	-245.161
484.000	23.333	-234.680
507.600	22.227	-224.572
531.200	19.931	-211.375
554.800	17.767	-203.241
578.400	17.636	-194.613
602.000	14.607	-186.545
625.600	12.479	-182.049
649.200	13.075	-174.839
672.800	12.891	-168.320
696.400	12.583	-160.468
720.000	11.250	-156.267
743.600	10.213	-149.642
767.200	10.187	-145.328
790.800	11.269	-143.144
814.400	11.081	-137.557
838.000	10.509	-132.750
861.600	10.063	-129.254
885.200	10.172	-124.495
908.800	10.745	-120.568
932.400	10.841	-118.100
956.000	10.884	-113.395
979.600	12.260	-109.552
1003.20	12.984	-105.975
1026.80	14.508	-103.110
1050.40	16.625	-99.886
1074.00	19.260	-98.149
1097.60	22.799	-98.605
1121.20	23.285	-99.907
1144.80	21.149	-100.925
1168.40	18.956	-99.639
1192.00	16.434	-98.425
1215.60	14.377	-95.033
1239.20	13.743	-92.553
1262.80	12.711	-89.249
1286.40	12.776	-86.081
1310.00	12.598	-82.581

Table.2 Coefficients for Figure 7

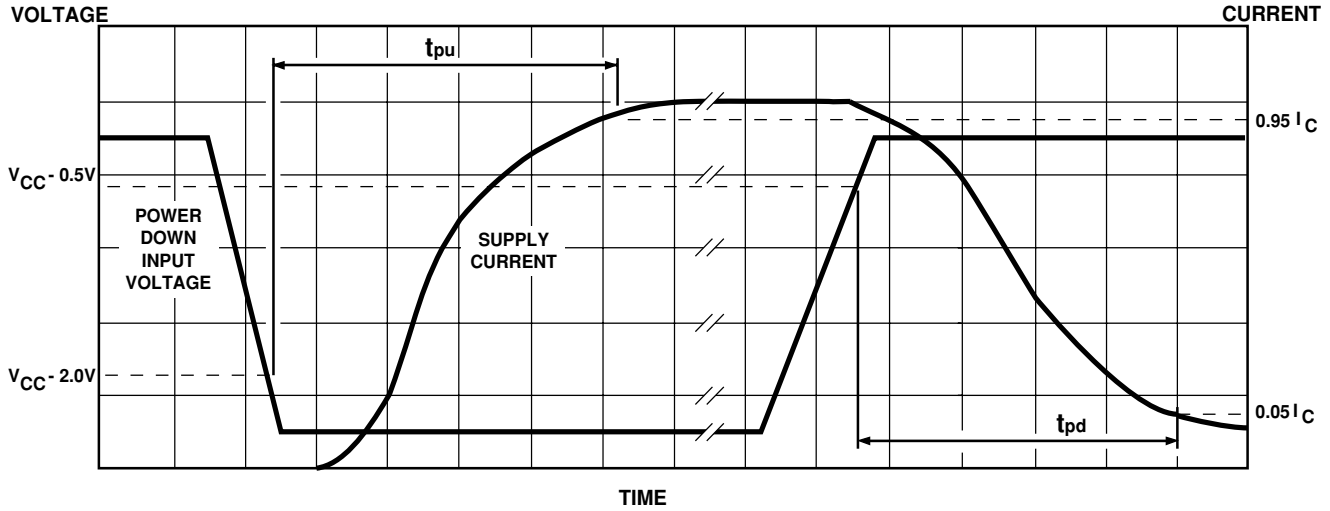


Figure 8 Power Up and Power Down

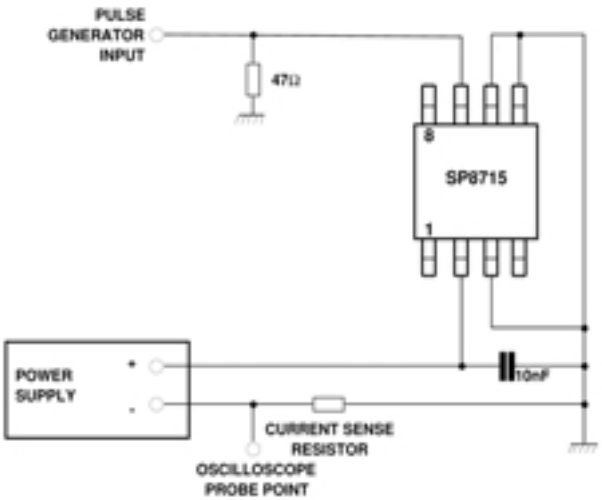
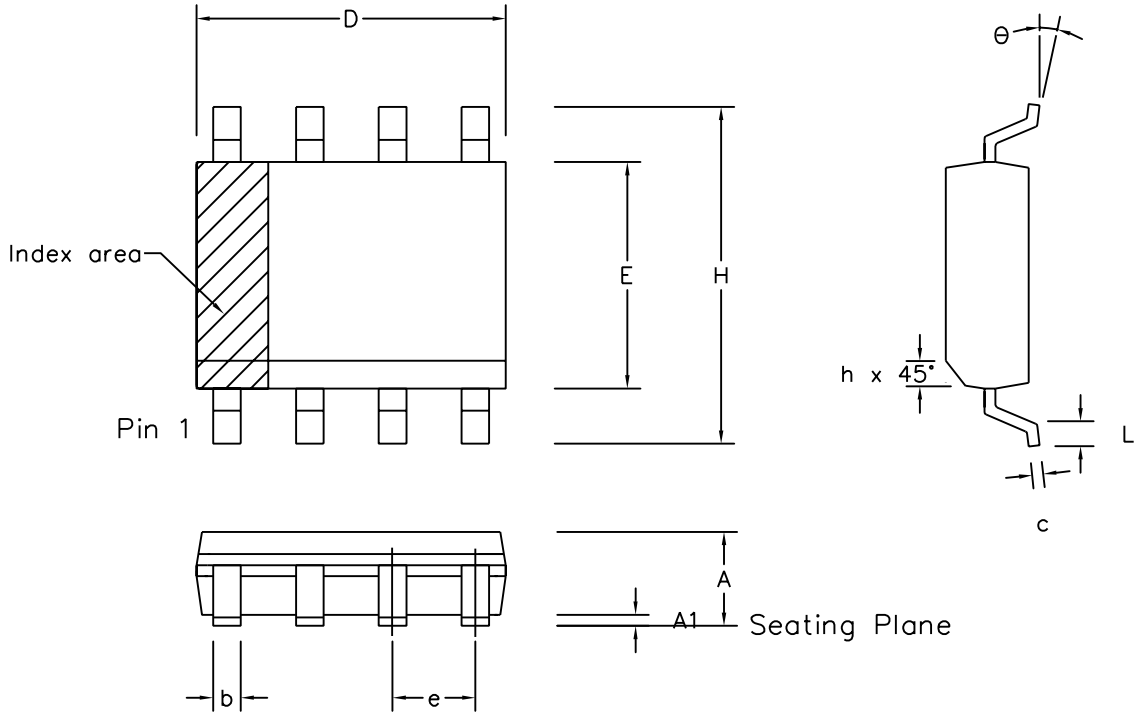


Figure 9 Power-Down Time Test Circuit



	Min mm	Max mm	Min inch	Max inch
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	5.00	0.189	0.197
H	5.80	6.20	0.228	0.244
E	3.80	4.00	0.150	0.157
L	0.40	1.27	0.016	0.050
e	1.27 BSC		0.050 BSC	
b	0.33	0.51	0.013	0.020
c	0.19	0.25	0.008	0.010
θ	0°	8°	0°	8°
h	0.25	0.50	0.010	0.020
	Pin Features			
N	8		8	
Conforms to JEDEC MS-012AA Iss. C				

Notes:

1. The chamfer on the body is optional. If not present, a visual index feature, e.g. a dot, must be located within the cross-hatched area.
2. Controlling dimensions are in inches.
3. Dimension D do not include mould flash, protusion or gate burrs. These shall not exceed 0.006" per side.
4. Dimension E1 do not include inter-lead flash or protusion. These shall not exceed 0.010" per side.
5. Dimension b does not include dambar protusion / intrusion. Allowable dambar protusion shall be 0.004" total in excess of b dimension.

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APPRD.					

ZARLINK SEMICONDUCTOR

Previous package codes

MP / S

Package Code DC

Package Outline for 8 lead SOIC (0.150" Body width)

GPD00010

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